

# INTRODUCING MULTI-BEAM HIGH DENSITY (HD) CONNECTORS

- Enable high current density with power contacts that carry up to 135A each
- Facilitate modularity with flexible contact quantities, positions and types



TE Connectivity's MULTI-BEAM High Density (HD) connectors offer higher current in less PCB space with up to 135A per power contact, featuring high density power and signal which saves space and reduces overall power consumption. The scalable and modular design also supports greater flexibility in configuration and PCB design.

## KEY BENEFITS

- Enable high current density with power contacts that carry up to 135A each
- Facilitate modularity with flexible contact quantity and number of positions, and high and low power contact types
- Support up to 15 signals with integrated signal contacts in each end module
- Decrease new tooling investment with a tooling platform common for all configurations
- Reduce the total cost of current capacity with higher available current per contact
- Help improve reliability with low resistance and voltage drop

## STANDARDS & SPECIFICATIONS

- EIA-364-23
- EIA-364-6
- EIA-364-21
- Compliant to UL-94 V0

## LEARN MORE

[MULTI-BEAM High Density \(HD\) Connectors Landing Page](#)

[MULTI-BEAM High Density \(HD\) Connectors Quick Reference Guide \(English\)](#)

[MULTI-BEAM High Density \(HD\) Connectors Quick Reference Guide \(Simplified Chinese\)](#)

## APPLICATIONS

- Servers
- Switches
- Routers
- Telecommunications Equipment
- Factory Automation
- Power Systems

## ELECTRICAL

Current carrying capacity:

- High power contact: 100 Amp Normal, 135 Amp Max.
- Lower power contact: 32Amp Normal, 42Amp Max.
- Contact resistance: 0.7 milliohm per contact at rated current.

## MECHANICAL

- Durability: 500 mating cycles max.
- Mechanical Shock: 50G per EIA-364 standard
- Vibration: 4.9G, 20-500Hz
- Operating temperature: -40°C to 125°C
- Mating force:
  - High power: 3.5N max. per contact
  - Lower power: 1.5N max. per contact
  - Signal contact: 1.0 N max. per contact

## MATERIALS

- Contact: High conductivity copper alloy
- Housing: glass filled LCP

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